

# N-Channel 180 V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)		
180	0.042 at V <sub>GS</sub> = 10 V	35		

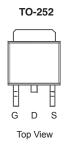
#### **FEATURES**

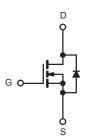
- DT-Trench Power MOSFET
- 100 %  $R_g$  and  $\,$  IS Tested



#### **APPLICATIONS**

· Primary Side Switch





N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>A</sub> = 25 °C, unless otherwise noted)							
Parameter		Symbol	Limit	Unit			
Drain-Source Voltage		V <sub>DS</sub>	180	V			
Gate-Source Voltage	V <sub>GS</sub>	± 20	v				
Continuous Design Company /T = 475 °C)h	T <sub>C</sub> = 25 °C	1	35				
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 125 °C	l <sub>D</sub> –	19				
Pulsed Drain Current		I <sub>DM</sub>	140	Α			
Continuous Source Current (Diode Conduction)	I <sub>S</sub>	30					
Avalanche Current		I <sub>AS</sub>	30				
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	24	mJ			
Mayimum Dayor Dissination	T <sub>C</sub> = 25 °C	В	85 <sup>b</sup>	W			
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub> _	6 <sup>a</sup>	T VV			
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C			

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Junction-to-Ambient <sup>a</sup>	t ≤ 10 s	- R <sub>thJA</sub>	13	18	°C/W	
Junction-to-Ambient*	Steady State		27	50		
Junction-to-Case (Drain)		R <sub>thJC</sub>	0.85	1.1		

- Notes:
  a. Surface mounted on 1" x 1" FR4 board.
- b. See SOA curve for voltage derating.

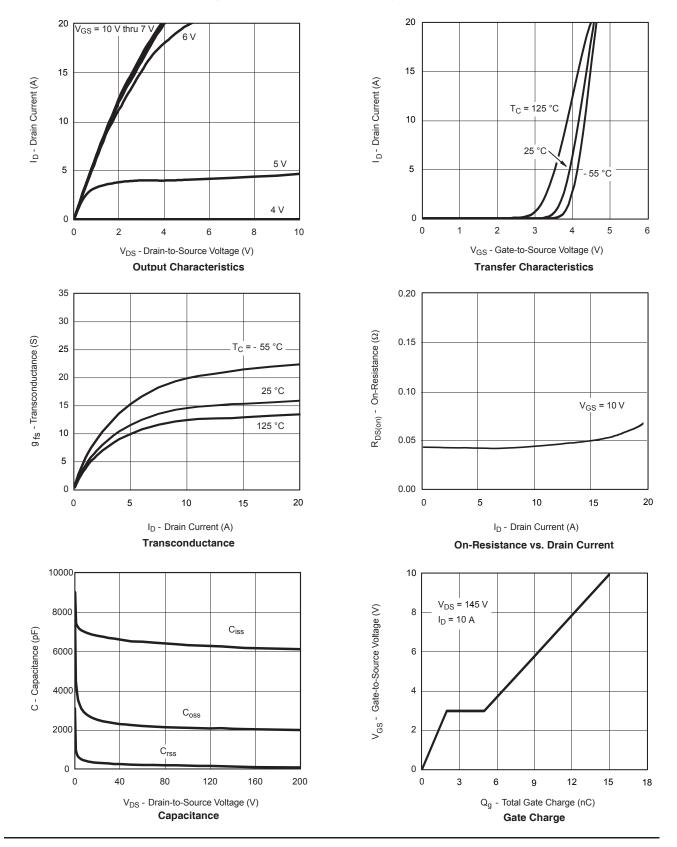
Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 uA	180			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \text{ uA}$	2		4	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 145 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	$I_{DSS}$	V <sub>DS</sub> = 145 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	uA	
		V <sub>DS</sub> = 145 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 175 °C			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	35			Α	
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		0.042	0.046	Ω	
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 145 V, I <sub>D</sub> =10A		16		S	
Dynamic <sup>a</sup>							
Input Capacitance	C <sub>iss</sub>			6750		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 145 V, F = 1 MHz		1250			
Reverse Transfer Capacitance	C <sub>rss</sub>			180			
Total Gate Charge <sup>c</sup>	Qg			15			
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 145 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		8		nC	
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			12			
Gate Resistance	R <sub>g</sub>		1.2		2.9	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			11	27		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 145  V,  R_L = 5.2  \Omega$		34	76		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		22	48	ns	
Fall Time <sup>c</sup>	t <sub>f</sub>			45	90		
Source-Drain Diode Ratings and Chara	acteristics (7	T <sub>C</sub> = 25 °C)					
Continous Source-Drain Diode Current	Is	T <sub>C</sub> = 25 °C			30	^	
Pulsed Current	I <sub>SM</sub>				140	Α	
Diode Forward Voltage <sup>b</sup>	V <sub>SD</sub>	I <sub>F</sub> = 19 A, V <sub>GS</sub> = 0 V		0.7	1.5	V	
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 19 A, dI/dt = 100 A/òs		160	250	ns	

#### Notes:

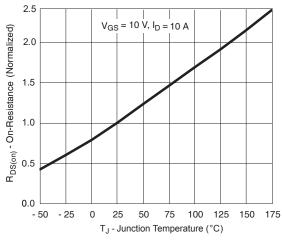
- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300 òs, duty cycle  $\leq$  2 %. c. Independent of operating temperature.

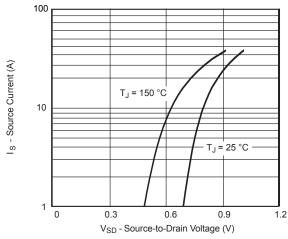
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



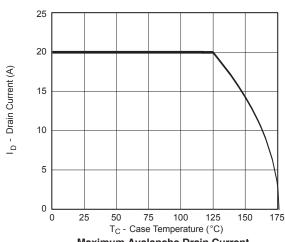
## **TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

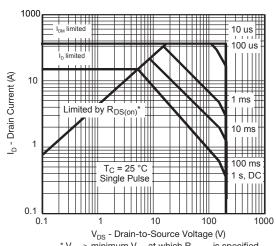




On-Resistance vs. Junction Temperature

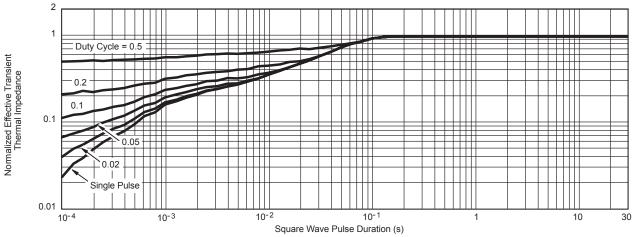






Maximum Avalanche Drain Current vs. Case Temperature

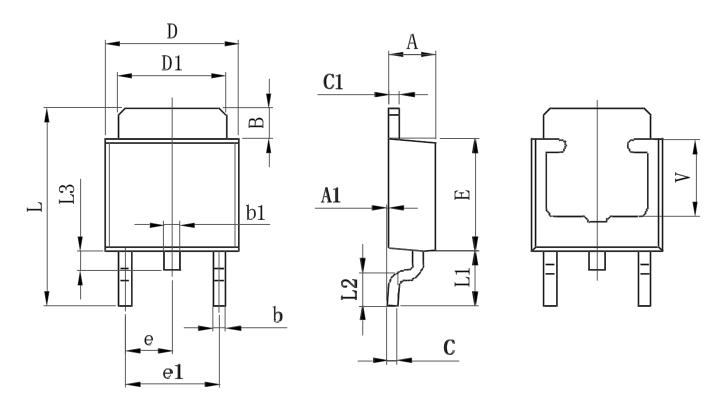
\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified **Safe Operating Area** 



Normalized Thermal Transient Impedance, Junction-to-Case

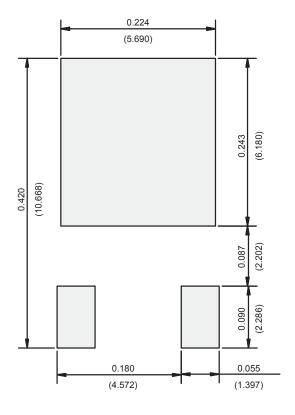


# **TO-252-2L PACKAGE OUTLINE DIMENSIONS**



Symbol	Dimensions	In Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
В	1.350	1.650	0.053	0.065	
b	0.500	0.700	0.020	0.028	
b1	0.700	0.900	0.028	0.035	
С	0.430	0.580	0.017	0.023	
c1	0.430	0.580	0.017	0.023	
D	6.350	6.650	0.250	0.262	
D1	5.200	5.400	0.205	0.213	
E	5.400	5.700	0.213	0.224	
е	2.300 TYP.		0.091	TYP.	
e1	4.500	4.700	0.177	0.185	
L	9.500	9.900	0.374	0.390	
L1	2.550	2.900	0.100	0.114	
L2	1.400	1.780	0.055	0.070	
L3	0.600	0.900	0.024	0.035	
V	3.800 REF.		0.150 REF.		

## RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)



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